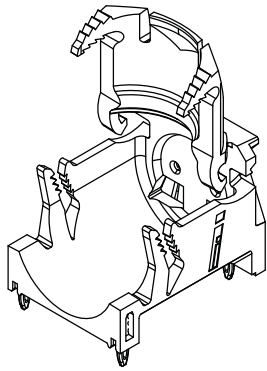
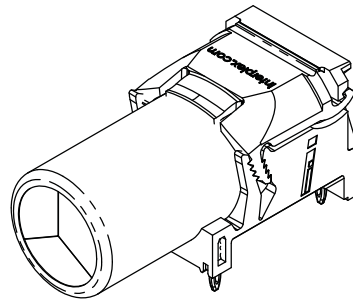


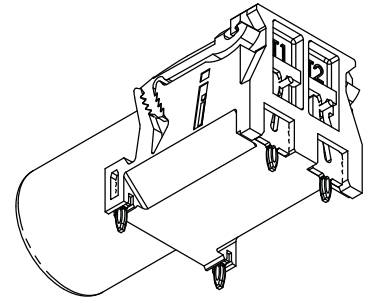
PRODUCT OUTLINE



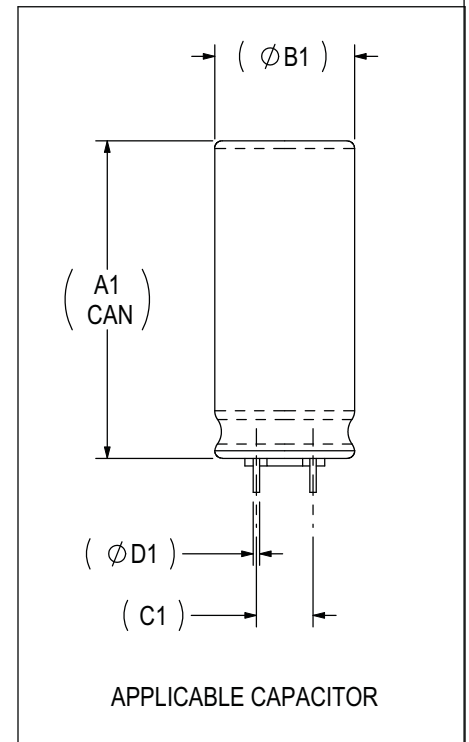
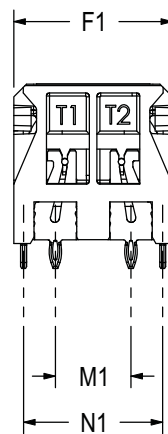
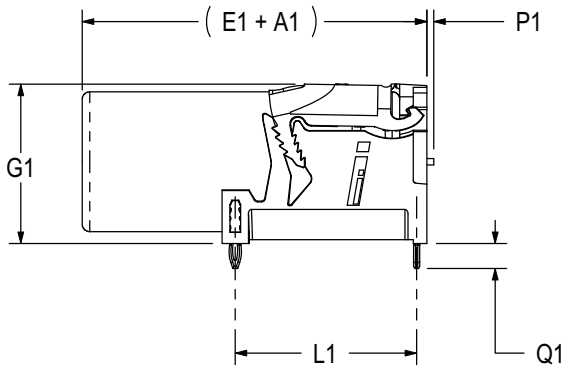
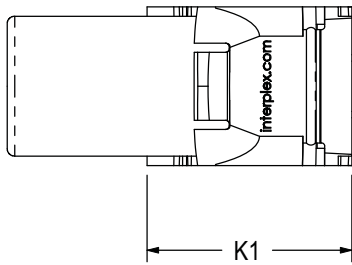
Cap-Loc Housing without Capacitor



With 42mm Capacitor

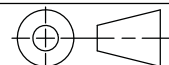


With 20mm Capacitor

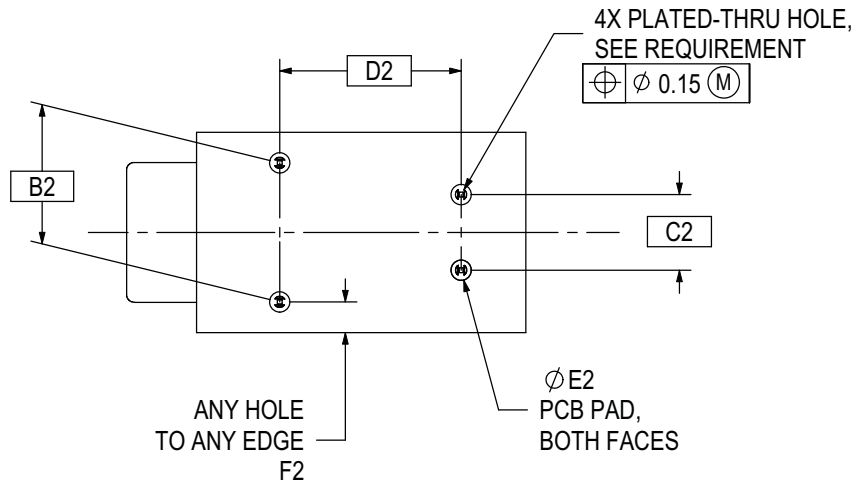
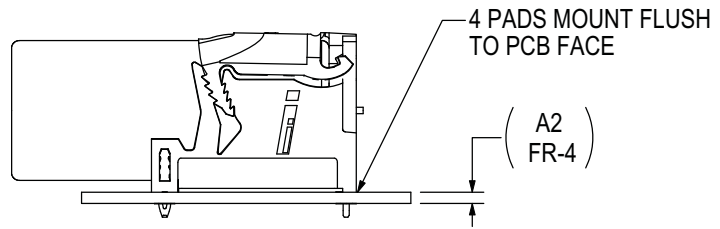
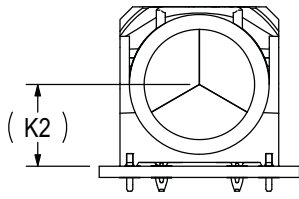


DIMENSIONS

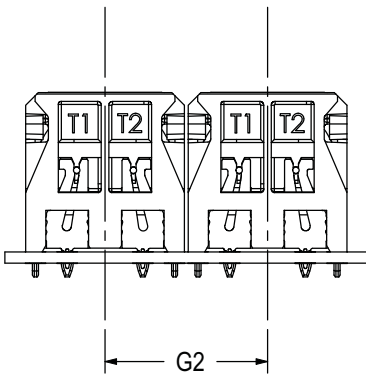
	A1	B1	C1	D1	E1	F1	G1	K1	L1	M1	N1	P1	Q1				
mm	42 20 REF	18.5 18.0 REF	7.5 REF	.85 .75 REF	3.73 3.47	21.3 20.7	21.35 MAX	27.3 26.9	24.2 23.8	10.2 9.8	18.6 18.2	0.3 MAX	3.5 3.1				



PCB MOUNTING



MINIMUM SPACING



PCB AND PLATED-THRU HOLE REQUIREMENT

	mm	in
DRILL	$\phi 1.613 \pm 0.025$	$\phi .0635 \pm .0010$
COPPER THICKNESS	0.025 Min	.0010 Min
FINAL IMMERSION PLATED HOLE DIAMETER	$\phi 1.486 \pm 0.076$	$\phi .0585 \pm .0030$
PCB LAMINATE	FR-4, $T_g > 150C$, 1.5mm Min Thickness	

DIMENSIONS

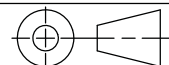
	A2	B2	C2	D2	E2	F2	G2	K2							
mm	1.5 MIN	18.4	10	24	2.4 MIN	2 MIN	21.5 MIN	10.8 REF							



PRODUCT DATA

PATENT PENDING. ALL RIGHTS RESERVED.
 TRADEMARKS ARE THE PROPERTY OF THEIR RESPECTIVE OWNERS.
 SPECIFICATIONS SUBJECT TO CHANGE WITHOUT NOTICE.

3RD ANGLE PROJECTION



PACKAGE DESIGNATOR:
CAP-LOC™ 18

TITLE: **CAPACITOR HOLDER, 18MM**

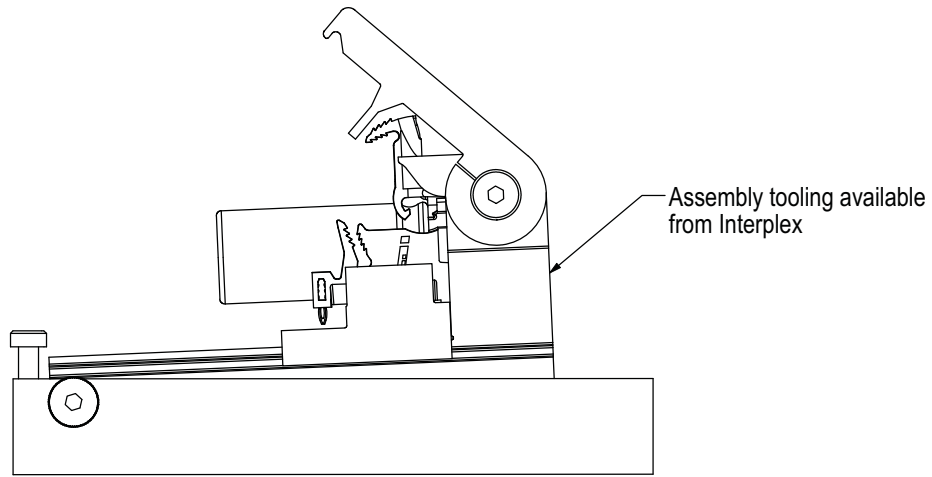
DOCUMENT NO.
IPX15108

REV
A

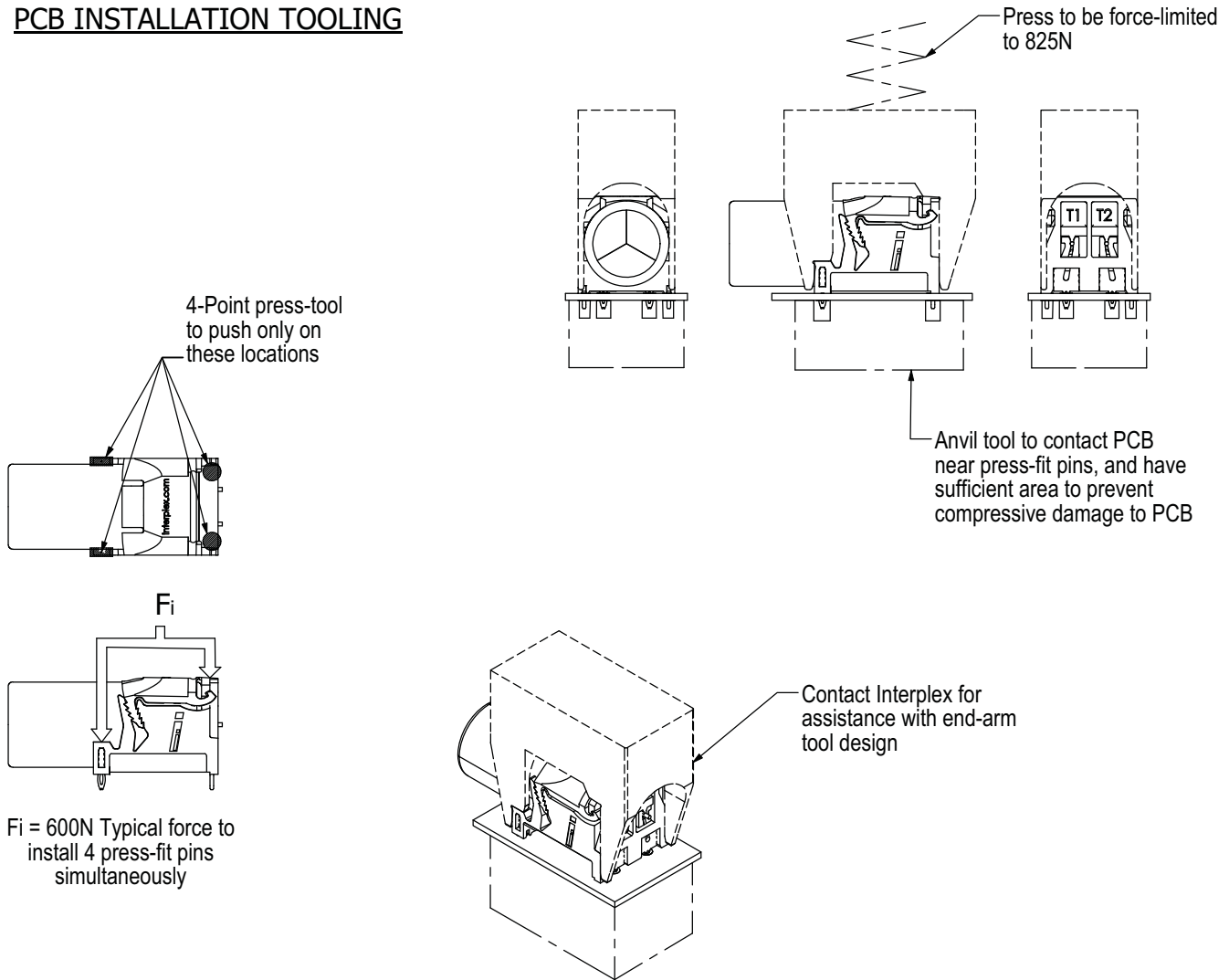
DATE
 11SEP2009

SHEET
 2 OF 6

CAPACITOR ASSEMBLY TOOLING



PCB INSTALLATION TOOLING

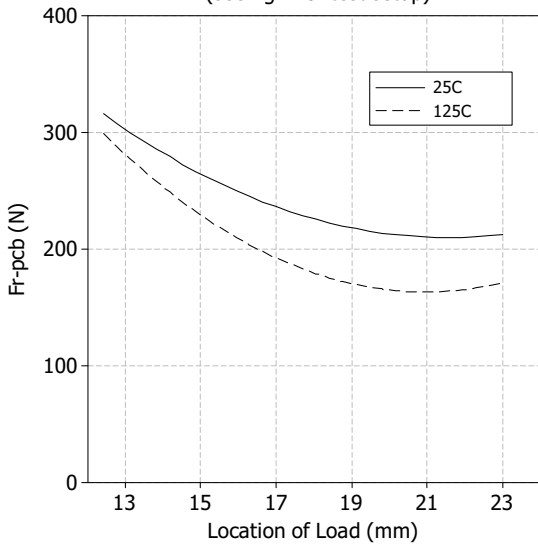


GENERAL CHARACTERISTICS

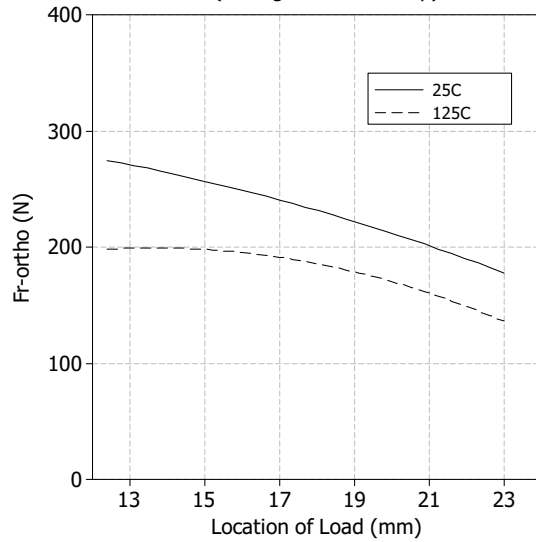
	PARAMETER	MIN	TYP	MAX	UNITS	CONDITIONS
Fi	Insertion Force, Housing to PCB		550		N	See PCB hole requirements
Fr-pcb	Retention Force, Housing to PCB	50	250			See Fig. 1
Fr-ortho	Retention Force, Capacitor to Housing, Orthogonal to PCB		200			See Fig. 2
Fr-axial	Retention Force, Capacitor to Housing, Axial to Capacitor		125			See Fig. 3
Fn	Normal Force, Contact to Capacitor Lead	2.5	3.4	4.3	kgf	
Rsum	Resistance, Capacitor Lead to PCB		1.00		milliohm	4-Wire test, Tin over nickel contact plating
R1	Resistance, Capacitor Lead to Contact		0.30			
R2	Resistance, Press-fit Eye to PCB		0.15			

RETENTION FORCE CURVES

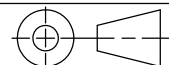
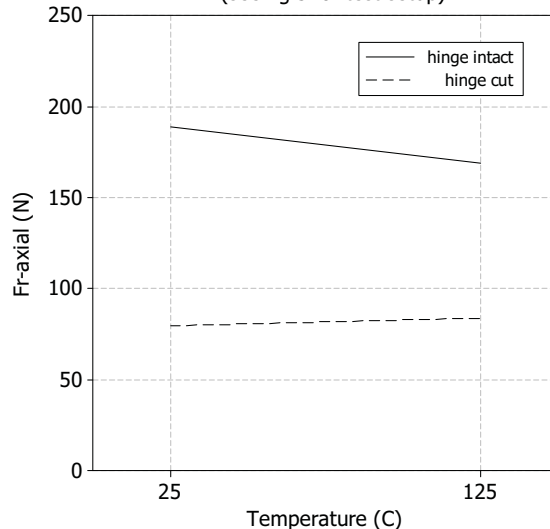
Graph 1) Typical Fr-pcb vs. Location of Load
(see fig.1 for test setup)



Graph 2) Typical Fr-ortho vs. Location of Load
(see fig.2 for test setup)



Graph 3) Typical Fr-axial vs. Temperature
(see fig.3 for test setup)



TEST SETUPS

FIG. 1 Fr-pcb

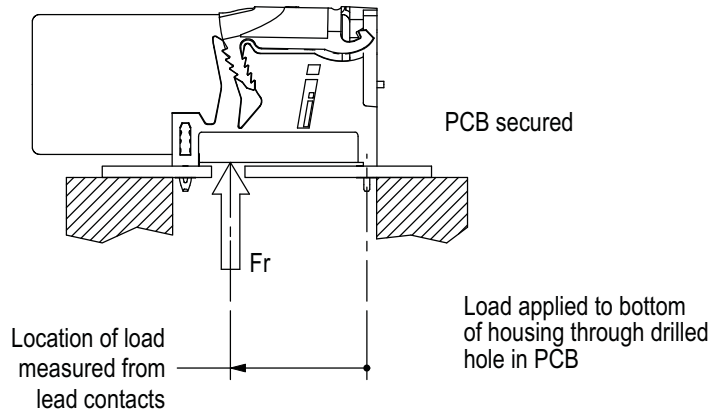


FIG. 2 Fr-ortho

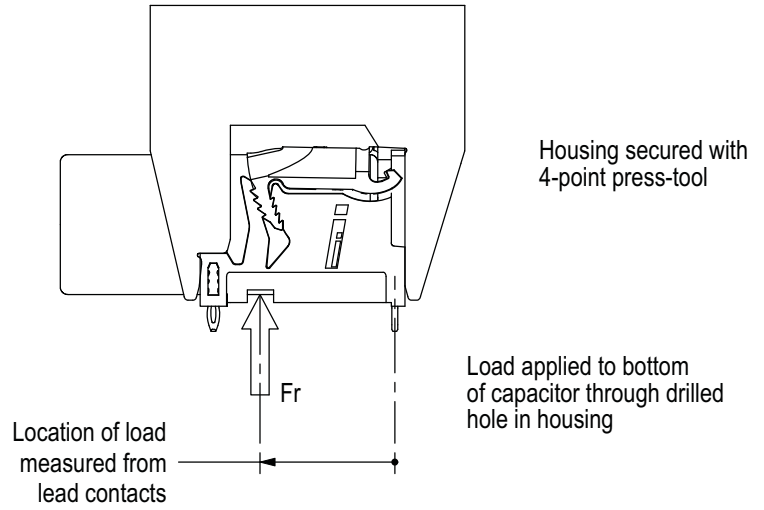
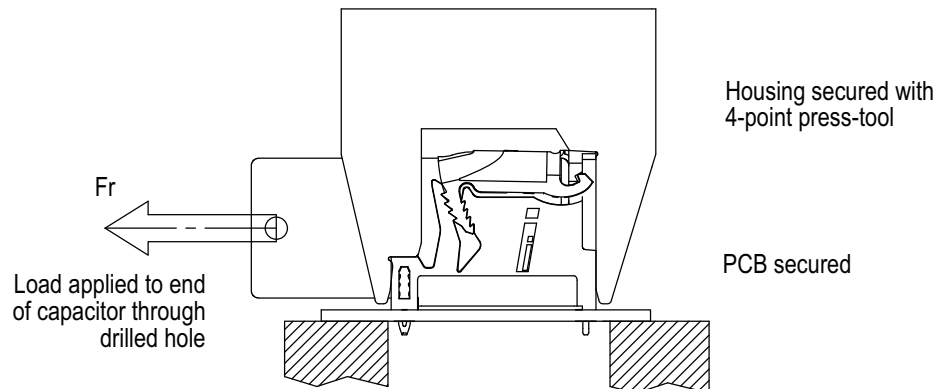


FIG. 3 Fr-axial



ORDERING INFORMATION

PART NUMBER	PACKAGING
TBD	Vacuum-Formed Trays

MATERIALS

INSULATOR	Nylon 66, 15%GF, UL94-HB
CONTACTS	High Strength Copper Alloy

CONTACT PLATING

TOP PLATE: Post-plated, Electrodeposited, Whisker-mitigated Matte Tin	0.4 - 1.1 um [15 - 45 uin]
UNDERPLATE: Post-plated, Electrodeposited, Sulfamate Nickel	1.5 - 3.0 um [60-120 uin]

All materials are RoHS compliant.

